BASIC BLADE & BEAM SOCKET

(0.50 mm) .0197" PITCH • BSH SERIES



BSH Mates:

SPECIFICATIONS

Insulator Material: Black LCP Contact Material: Phosphor Bronze Plating: Au or Sn over 50 µ" (1.27 µm) Ni Current Rating: 2 A per pin (2 pins powered) Operating Temp Range: -55 °C to +125 °C Voltage Rating: 175 VAC Max Cycles:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (030-090) (0.15 mm) .006" max (120-150)* *(.004" stencil solution may be available: contact IPG@samtec.com)

Board Stacking:

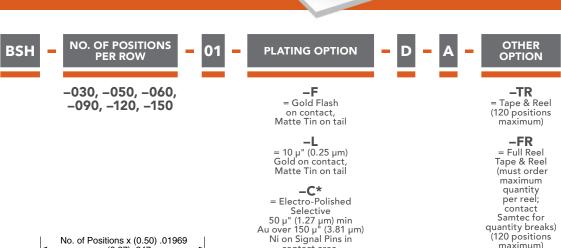
For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

ALSO AVAILABLE MOQ Required

 $30 \, \mu$ " (0.76 μ m) Gold **Edge Mount Capability** 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)

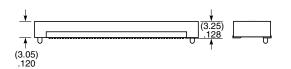


Some lengths, styles and options are non-standard, non-returnable.



contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails

(*–C Plating passes 10 year MFG testing)



(7.24)

.285

No. of Positions x (0.50) .01969

+ (6.27) .247



maximum)

Post

*Processing conditions will affect mated height.

NO. OF POSITIONS BSH OPTION **PER ROW** -030, -060, -090 -GP = Guide

= Gold Flash on contact, Matte Tin on tail

= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

